**AMENDMENTS TO THE CLAIMS** 

This listing of claims replaces all prior versions of claims in the application.

1. (Cancelled).

2. (Cancelled).

3. (Original): A quantum wire device comprising a single-crystal material made of

ceramic or metal, said single-crystal material internally having dislocations arranged one-

dimensionally on respective straight lines at a high density of 10<sup>6</sup> to 10<sup>14</sup> / cm<sup>2</sup>, and quantum

wires consisting of metal atoms introduced in said single-crystal material through a diffusion

treatment, said quantum wires being arranged along said corresponding dislocations at a high

density of  $10^6$  to  $10^{14}$  / cm<sup>2</sup>.

4. (Original): A thin film device comprising a single-crystal thin film made of ceramic

or metal, said thin film internally having dislocations arranged one-dimensionally on respective

straight lines at a high density of 10<sup>6</sup> to 10<sup>14</sup> / cm<sup>2</sup>, and nano-hole bundle formed along said

corresponding dislocations.

5. (Cancelled).

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6. (Previously presented): A method of producing a single-crystal material for a quantum

wire device, comprising:

compressing a single-crystal blank made of ceramic or metal, from a direction allowing

the activation of a single slip, in a temperature range of a brittle-to-ductile transition temperature

to about a melting point of said single-crystal blank to induce plastic deformation therein, and

subjecting the resulting product to a heat treatment at a high temperature of one-half or more of

said melting point by absolute temperature, to provide a single-crystal material internally having

dislocations arranged one-dimensionally on respective straight lines at a high density of 10<sup>6</sup> to

 $10^{14} / \text{cm}^2$ ; and

subjecting said single-crystal material to a diffusion treatment to diffuse metal atoms

from the surface of said single-crystal material to form quantum wires arranged along said

corresponding dislocations at a high density of 10<sup>6</sup> to 10<sup>14</sup> / cm<sup>2</sup>.

7. (Previously presented): A method of producing a single-crystal material for a thin film

device, comprising:

compressing a single-crystal blank made of ceramic or metal, from a direction allowing

the activation of a single slip, in a temperature range of a brittle-to-ductile transition temperature

to about a melting point of said single-crystal blank to induce plastic deformation therein, and

subjecting the resulting product to a heat treatment at a high temperature of one-half or more of

said melting point by absolute temperature, to provide a single-crystal material internally having

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dislocations arranged one-dimensionally on respective straight lines at a high density of  $10^6$  to  $10^{14} \, / \, \mathrm{cm}^2$ : and

subjecting said single-crystal material to annealing or chemical etching to form nano-hole bundles along said corresponding dislocations.